

SOD-523 Plastic-Encapsulate ESD Protection Diodes

DESCRIPTION

The ESD5B3CM is designed to protect voltage sensitive component from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, portable devices, digital cameras, power supplies and many other portable applications where board space comes at a premium. Also because of its low capacitance, it is suited for use in high frequency designs such as high speed line application.

This device has been specifically designed to protect sensitive components which are connected to data and transmission lines from overvoltage caused by ESD (electrostatic discharge), and EFT (electrical fast transients).

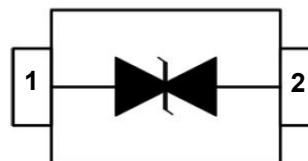
Features

- ◆ Peak power dissipation: 400W (8/20μs)
- ◆ IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- ◆ IEC61000-4-4 (EFT) 40A (5/50ns)
- ◆ Protects one directional I/O line
- ◆ Low clamping voltage
- ◆ Low leakage current
- ◆ Low capacitance
- ◆ Working voltages : 3.3V
- ◆ Meets MSL 3 Requirements

Pin Configuration



Circuit Diagram



Applications

- ◆ High Speed Line
- ◆ Serial and Parallel Ports
- ◆ Notebooks, Desktops, Servers
- ◆ Projection TV
- ◆ Cellular handsets and accessories
- ◆ Portable instrumentation
- ◆ Peripherals

Mechanical Characteristics

- ◆ Package: SOD-523
- ◆ Flammability Rating: UL 94V-0
- ◆ High temperature soldering guaranteed: 260 °C / 10s
- ◆ Packaging: Tape and Reel
- ◆ Weight: 0.001 gram (approx.)
- ◆ Marking: 3CM

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
ESD per IEC 61000-4-2 (Air)	VESD	± 30	KV
ESD per IEC 61000-4-2 (Contact)		± 30	
Peak Pulse Power(8/20us)	P _{PP}	400	W
Operating Temperature	T _{OPT}	-55 to +150	°C
Storage Temperature	T _{STG}	-55 to +150	°C
Lead Solder Temperature – Maximum (10 Second Duration)	T _L	260(10 sec.)	°C

The above data are for reference only.

Electrical Characteristics (T_A=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V _{RWM}	Reverse Working Voltage				3.3	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA	4.0		6.0	V
I _R	Reverse Leakage Current	V _{RWM} = 3.3V			1.0	μA
V _C	Clamping Voltage	I _{PP} = 1A, t _p = 8/20μs			6.5	V
V _C	Clamping Voltage	I _{PP} = 23A, t _p = 8/20μs		13	18	V
C _J	Junction Capacitance	V _R = 0V, f = 1MHz		38	45	pF

The above data are for reference only.

ELECTRICAL CHARACTERISTICS CURVE

Fig 1 8/20 μ s Waveform per IEC61000-4-5

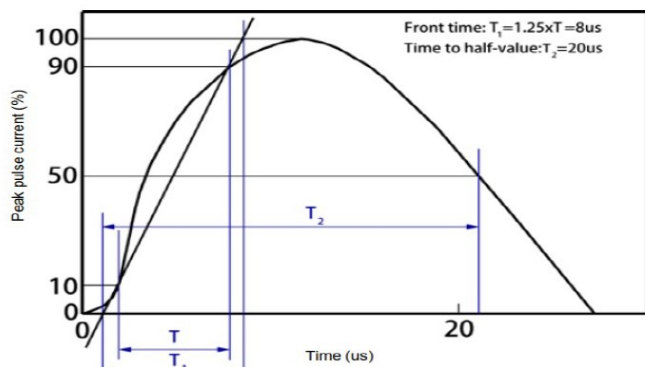


Fig 2 Contact Discharge Current Waveform per IEC 61000-4-2)

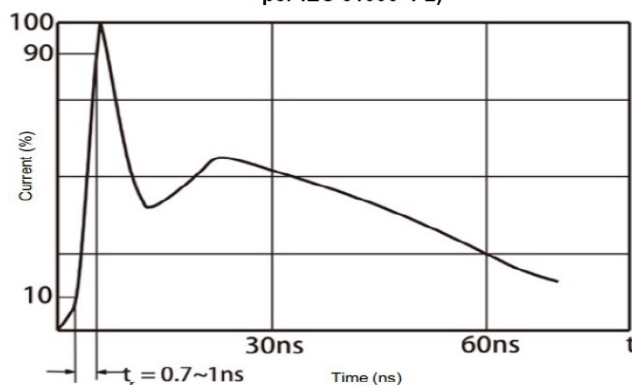


Fig 3 Voltage vs Capacitance

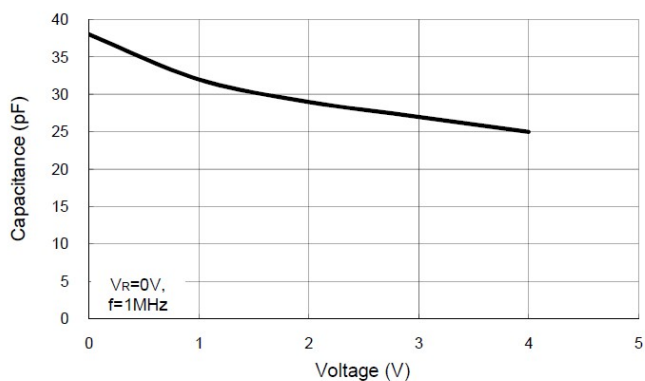
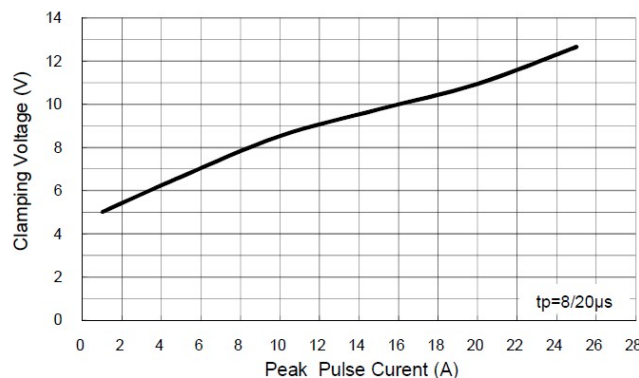


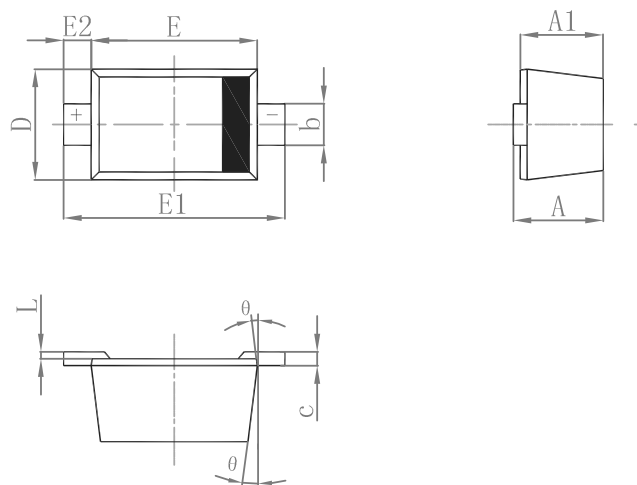
Fig 4 Clamping Voltage vs Peak Pulse Current



The curve above is for reference only.

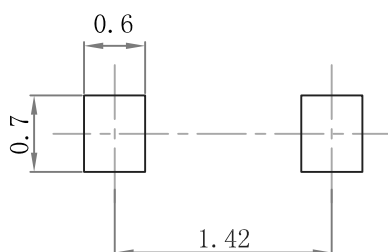
Outline Drawing

SOD-523 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
K	7° REF		7° REF	

Suggested Pad Layout



Note:

1. Controlling dimension: in/millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

PACKAGE SPECIFICATIONS

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (pcs)	Box Size (mm)	QTY/Box (pcs)	Carton Size (mm)	Q'TY/Carton (pcs)
SOD-523	7'	178	3000	183×188×80	45,000	386×265×215	180,000